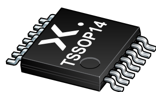


SOT402-1

plastic, thin shrink small outline package; 14 leads; 0.65 mm pitch; 5 mm x 4.4 mm x 1.1 mm body

30 January 2017 Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP14
Package type industry code	TSSOP14
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	18-2-2003
Manufacturer package code	SOT402

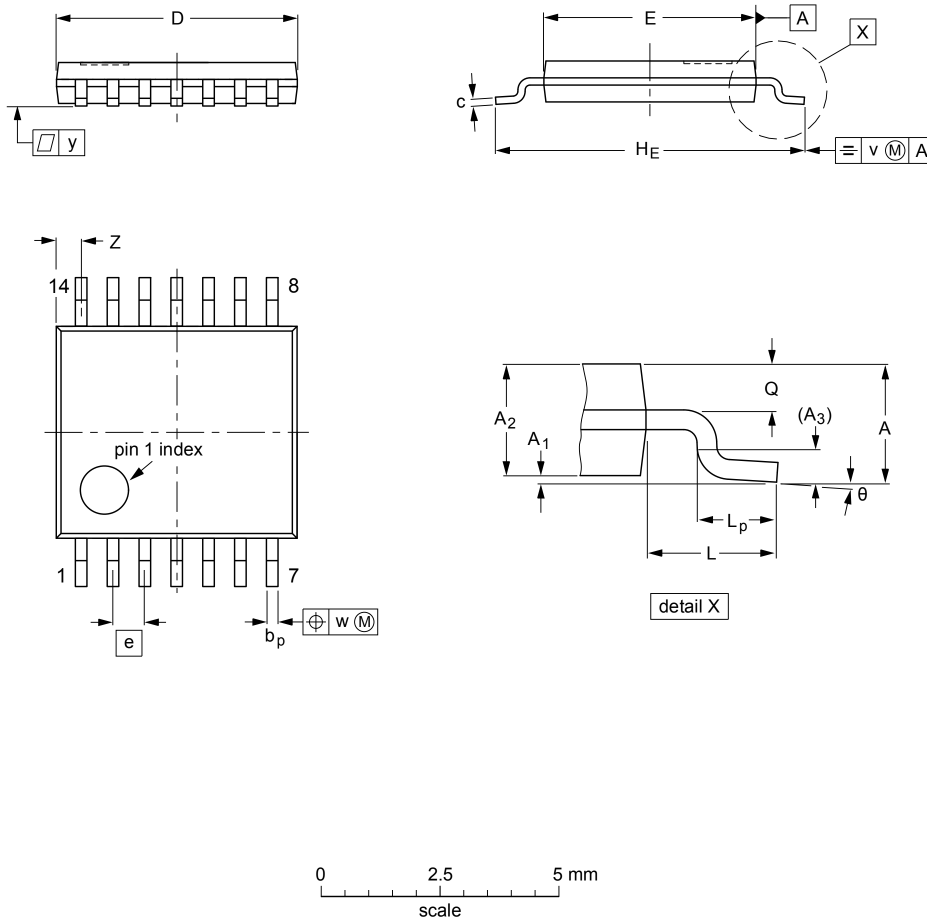
Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.9	-	5	5.1	mm
E	package width		4.3	-	4.4	4.5	mm
A	seated height		-	-	1.1	1.1	mm
A_2	package height		0.8	-	0.9	0.95	mm
e	nominal pitch		-	-	0.65	-	mm
n_2	actual quantity of termination		-	-	14	-	

nexperia

2. Package outline

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

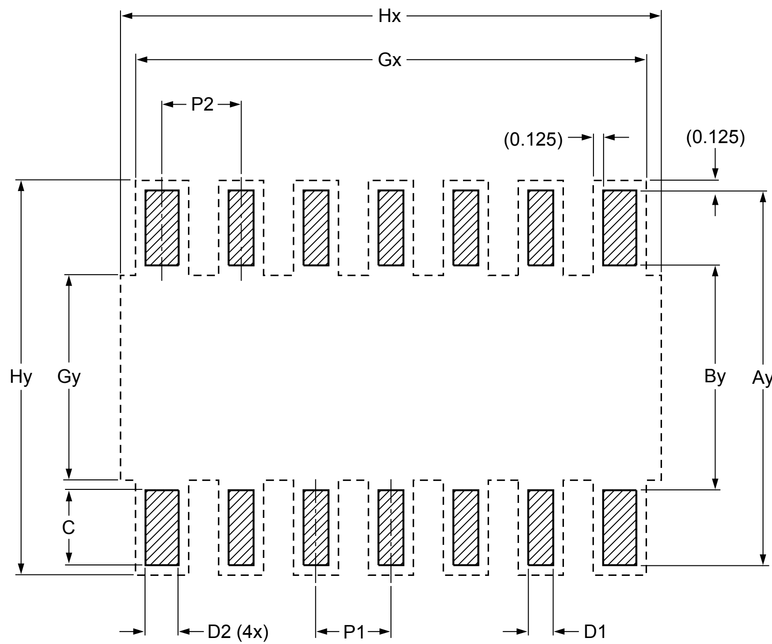
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				~~99-12-27~~ 03-02-18

Fig. 1. Package outline TSSOP14 (SOT402-1)

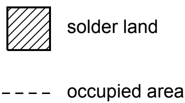
All information provided in this document is subject to legal disclaimers. © Nexperia B.V. 2017. All rights reserved

3. Soldering

Footprint information for reflow soldering of TSSOP14 package **SOT402-1**



Generic footprint pattern
Refer to the package outline drawing for actual layout



DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	4.950	5.300	5.800	7.450

sot402-1_fr

Fig. 2. Reflow soldering footprint for TSSOP14 (SOT402-1)

All information provided in this document is subject to legal disclaimers.
© Nexperia B.V. 2017. All rights reserved

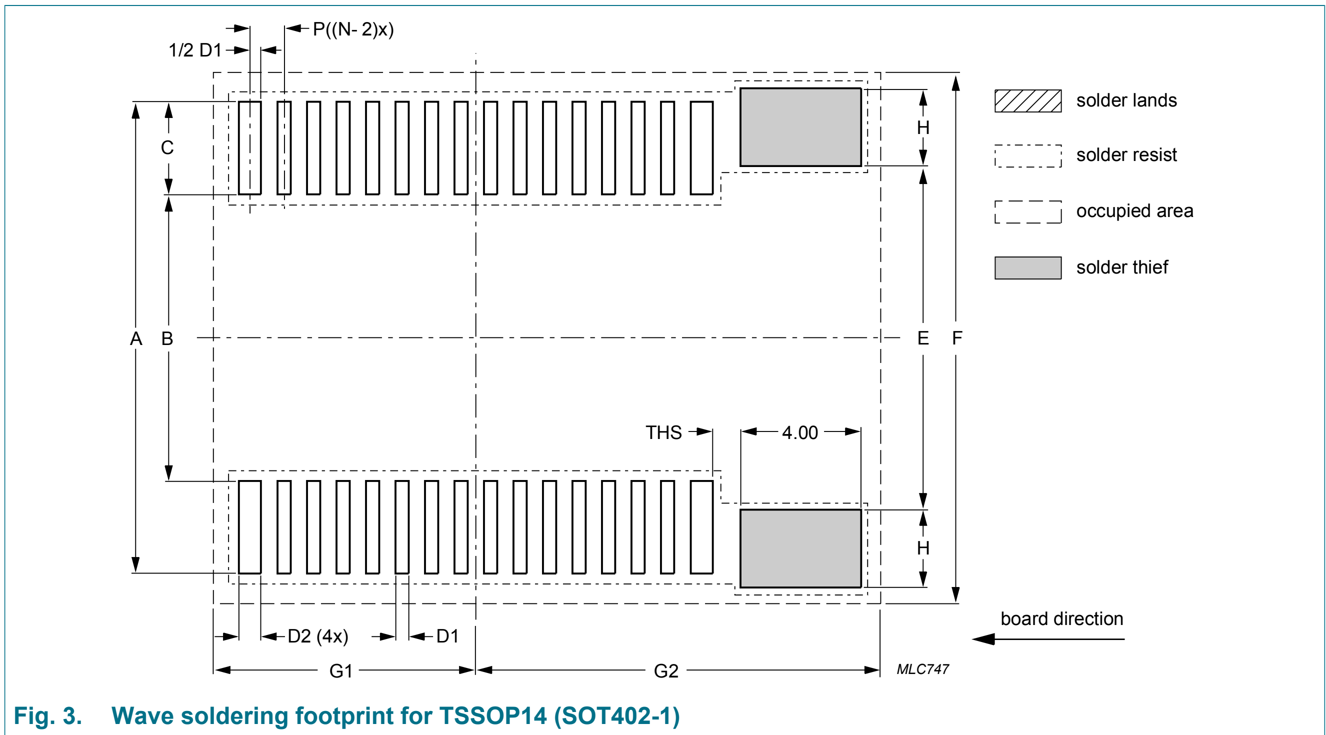


Fig. 3. Wave soldering footprint for TSSOP14 (SOT402-1)

All information provided in this document is subject to legal disclaimers.

© Nexperia B.V. 2017. All rights reserved

4. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia takes no responsibility for the content in this document if provided by an information source outside of Nexperia.

In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of Nexperia.

Right to make changes — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

All information provided in this document is subject to legal disclaimers.

© Nexperia B.V. 2017. All rights reserved

5. Contents

1. Package summary... 1
2. Package outline.. 2
3. Soldering.. 3
4. Legal information.. 5

© Nexperia B.V. 2017. All rights reserved

For more information, please visit: http://www.nexperia.com
For sales office addresses, please send an email to: salesaddresses@nexperia.com
Date of release: 30 January 2017